



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 10/625,166  
 Filing Date ..... July 22, 2003  
 Confirmation No. .... 8008  
 Inventor ..... Janos Fucsko et al.  
 Assignee ..... Micron Technology, Inc.  
 Group Art Unit ..... 2813  
 Examiner ..... Erik J. Kielin  
 Attorney's Docket No. .... MI22-2246  
 Customer No. .... 021567  
 Title: Wet Etching Method of Removing Silicon From a Substrate (as Amended)

**RESPONSE TO APRIL 18, 2005 OFFICE ACTION**

To: Mail Stop Amendment  
 Commissioner for Patents  
 P. O. Box 1450  
 Alexandria, VA 22313-1450

**VIA U.S. EXPRESS MAIL**

From: Mark Matkin (Tel. 509-624-4276; Fax 509-838-3424)  
 Wells St. John P.S.  
 601 West First Avenue, Suite 1300  
 Spokane, WA 99201-3828

Responsive to the Office Action dated April 18, 2005, Applicant amends and remarks as follows:

**AMENDMENTS**

## **Amendments to the Title**

Please amend the title as follows:

WET ETCHING METHOD OF REMOVING SILICON  
FROM A SUBSTRATE ~~AND METHOD OF FORMING~~  
~~TRENCH ISOLATION~~